Tera microCORE Chipset

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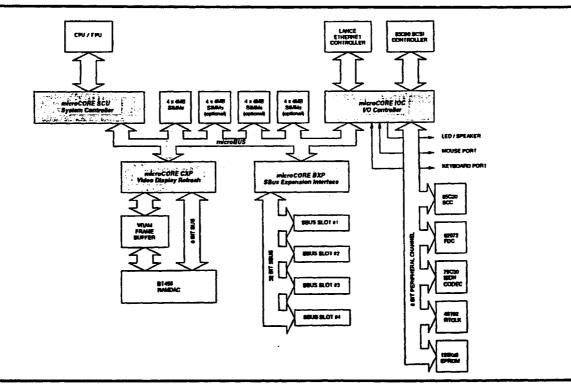
- Most highly integrated SPARC chipset available
- Integrates cache, memory management, DRAM control, I/O, color video display control, and Sbus interface into four components
- Reduces component count of SPARC-compatible system by 50%
- Supports laptop or SLC-class machine with minimal two-chip configuration
- 25/33/40 MHz frequencies
- 1.0 μ and 0.8 μ CMOS technologies



- Minimize component count
- Allow QFP packaging option
- Simplify board design
 - VLSI building blocks, no glue
 - Easy high frequency operation



System Block Diagram



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System Controller (SCU)

- Direct interface to SPARC integer/floating point unit Weitek, Cypress/Ross, Fujitsu, LSI Logic
- Instruction and data caches
 4KB/4KB, physical, direct-mapped, write-through
- Write buffer
 8 words deep; byte and doubleword merging
- SPARC Reference MMU 64-entry fully-associative TLB, hardware TLB miss handling
- Memory controller Up to 64 MB of DRAM, 2-way & 4-way page interleaving, SRAM/EPROM support
- microBUS controller
 Multiplexed 36-bit address/data, centralized arbitration
- 224-pin CPGA, 224-pin PPGA

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I/O Controller (IOC)

- Direct interface to Ethernet controller Buffered interface to AMD Lance, block transfers to/from memory
- Direct interface to SCSI controller
 FIFO-buffered interface to NCR/Emulex 53C90 + DMA
- Direct interface to 8 byte-wide peripheral & memory devices Programmable interface, 3 undedicated DMA channels
- Monochrome video display controller Resolutions up to 1280x1024, DRAM-based frame buffer, h/w cursor
- Internal peripherals
 Interrupt controller, 3 counter/timers, 2 serial ports
- 208-pin PPGA, 208-pin QFP

- Component count Eliminates external SRAMs
- Cost Eliminates high-speed SRAMs
- **Physically-addressed cache** Software-transparent cache consistency
- Overlapped CPU execution/cache Fill Requested word returned first; early CPU release; streaming mode
- Scalability to higher frequencies Critical timing within a single chip
- Lower miss penalty 4-7 cycles vs. 13 cycles for SPARCstation1, 26 cycles for SPARCstation2



Comparison with SPARCstation 1 External Cache

	External 64KB DM	Integrated 4KB, 4KB, DM
I-Miss Ratio	3.6% (Unified)	9.4%
D-Miss Ratio	n/a	11.0%
Miss Penalty	13*	5.5
CPI Penalty	0.59	0.67
CPI	~2.00	~2.08
Performance	Baseline	-4%

* Note: SPARCstation 2 has 26 cycle miss penalty

Both assumes 1.25 references/instruction For Tera: 60% page hit rate, 4 cycles to first word on page hit 7 cycles to first word on page miss ...the most cost-effective memory interconnect

- Low pin count results in:
 - Die area reduction
 - Power reduction
 - QFP packaging
- Balanced CPU/memory bandwidth
- Simple bus protocol
- 111 Mbytes/sec at 33 MHz suitable for uniprocessing
- Support for innovative virtual DMA implementation

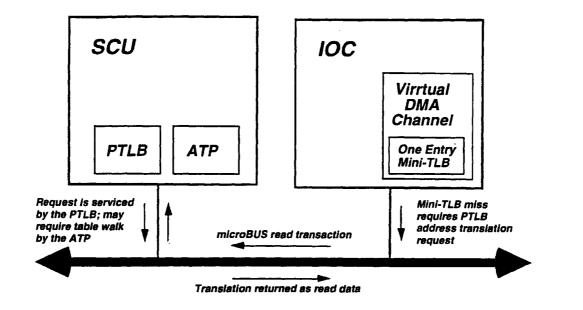


Direct Memory Access

- Physical DMA hardware or software chaining to support paged, virtual memory environment
- Virtual DMA all I/O traffic passes through the MMU
 - Simplifies hardware
 - Memory protection for free
 - Lower software overhead
- Tera Virtual DMA
 - Avoid MMU and/or bus bottlenecks
 - Applies to all bus masters



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Video Display Controller (CXP)

- Integrates frame buffer controller and video display controller
- 8-bits per pixel color and gray-scale displays
- Programmable display resolutions up to 1280 x 1024
- No external glue logic only RAMDAC and VRAMs
- Programmable video timing
- 32x32 two bits per pixel hardware cursor (X-compatible)

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• 160-pin PPGA, 160-pin QFP

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- Implements the full SBus B.0 specification
- Supports up to 4 SBus slots
- Handles transactions from the Memory Bus to SBus, from SBus to the Memory Bus, and between two SBus devices
- Dual 64 and 128-byte FIFO data buffers
- Asynchronous interface allows maximum 25 MHz SBus frequency, independent of system clock frequency
- 64-entry SPARC Reference TLB
- Integrated interrupt controller
- 208-pin PPGA, 208-pin QFP



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Competitive Advantage

- Optimized for low-cost systems
- Simple board design

No external high-speed SRAMs required

• Frequency Scalability

Critical timing internal to System Controller Unit

Highly Integrated Solution

Space & Power savings

Higher reliability

Lower manufacturing cost

• Components suited for a wide range of designs

